

Amendments to the Specification:

Please replace the title on page 1, line 1 with the following:

SEMICONDUCTOR PACKAGE WITH LEADFRAME INDUCTORS

Please amend the Abstract on page 11 as follows:

A semiconductor device in which an inductance element formed in a resin package has stable characteristics, impedance matching is achieved easily, and the stability of high-frequency characteristics is improved, more particularly a [[A]] semiconductor chip, a mold resin sealing the semiconductor chip, and a plurality of sealed within mold resin having a conductor leads lead extending from an inside of the mold resin to an outside thereof are provided. A portion of each the conductor lead arranged inside the mold resin forms an internal terminal portion, and a portion thereof arranged outside the mold resin forms an external terminal portion. An electrode of the semiconductor chip and the internal terminal portion of the conductor lead are connected. The internal terminal portion of at least one of the conductor leads forms an inductance element portion, at least a part of which is narrower than the external terminal portion of the conductor outside the mold resin. An inductance element formed in a resin package has stable characteristics, and the stability of high frequency characteristics improves.